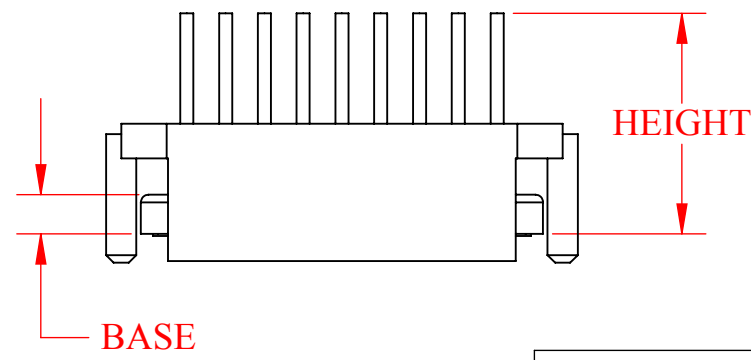
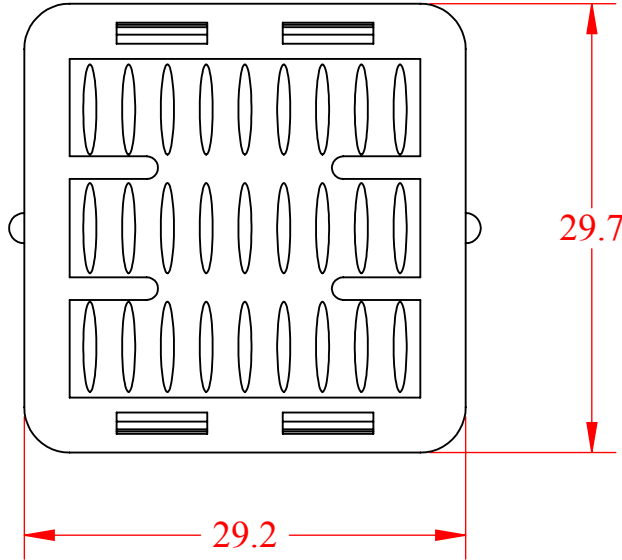
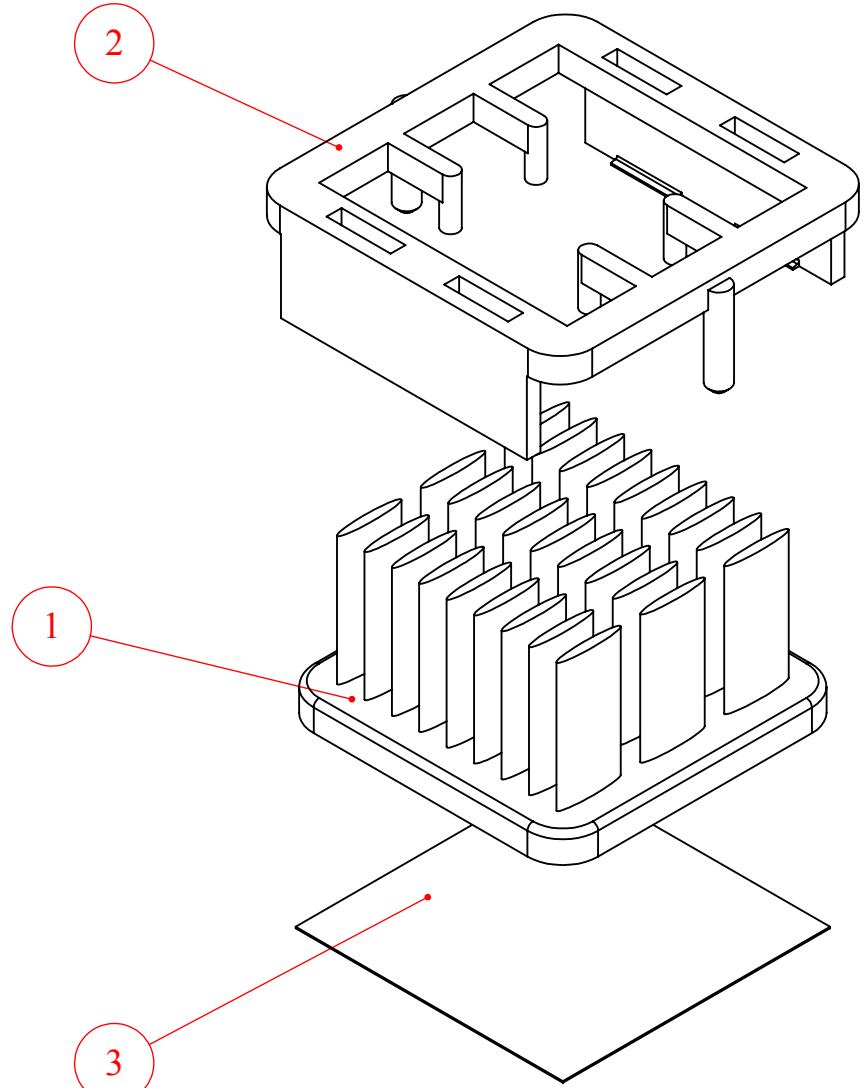


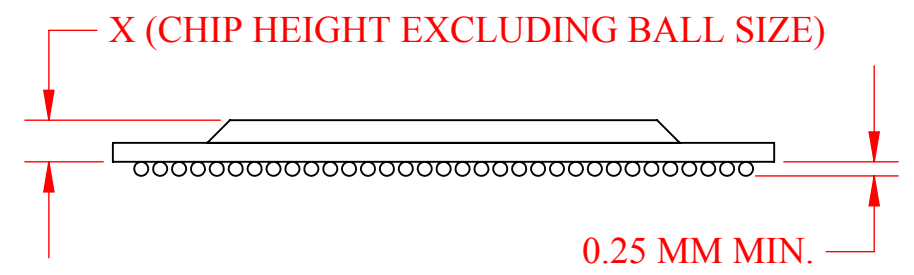
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REVISIONS			
REV.	DESCRIPTION	DATE	APPROVED
A	NEW RELEASE	9/22/05	FWANG
B	ECN#705211: UPDATED PAD SIZE AND CLIP	7/21/07	FWANG
C	PER ECN#005051	05/05/10	FWANG

EXPLODED VIEW



- NOTES:**
- SEE TABLE BELOW FOR COMPLETE PART NUMBER WITH OPTIONS.
 - RECOMMENDED KEEP-OUT AREA: 32X32 MM.
 - COLOR OF CLIP TO BE SELECTED BASED ON CHIP HEIGHT AS ILLUSTRATED BELOW.
 - CLIP FITS MIN. 0.25 MM SOLDER BALL HEIGHT.



X	CLIP COLOR
3.3±0.3 MM	YELLOW
1.7±0.3 MM	BLUE
0.9±0.3 MM	ORANGE

COMPLETE PART NUMBER WITH OPTIONS

ROOT	HEIGHT (hh)	BASE	CLIP (c)	PAD
INM27001-	15W (14.6 MM)	/2.6 (2.6 MM)	Y (YELLOW)	+T710
	18W (17.6 MM)			
	21W (20.6 MM)		BU (BLUE)	
	23W (22.6 MM)			
	28W (27.6 MM)			
33W (32.6 MM)	O (ORANGE)	+OTHER		
	K32			

EXAMPLE PART NUMBER: INM27001-23W/2.6BU+T710

ITEM NO.	PART NUMBER	DESCRIPTION	QTY.
1	INM27001-hhW/2.6	ELLIPTICAL HEAT SINK (SEE TABLE ON THE RIGHT FOR HEIGHT CODE hh)	1
2	BCP30-09(27)c	27 MM EZ-SNAP CLIP (SEE TABLE ON THE RIGHT FOR CLIP CODE c)	1
3	OPTIONAL	THERMAL PAD (25X25 MM OR FULL COVERAGE OF HEAT SINK BASE)	1

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MM TOLERANCES ARE: DECIMALS ANGLES X. ±.25 ±1° X.X ±.25 X.XX ±.10	CAD GENERATED DRAWING, DO NOT MANUALLY UPDATE		RADIAN HEATSINKS DIV. OF INTRICAST CO. INC. 2160 WALSH AVE SANTA CLARA, CA - 95050 27 MM ELLIPTICAL HEAT SINK
	APPROVALS	DATE	
	DRAWN	FWANG 9/22/05	
	CHECKED	TSIN 9/23/05	
MATERIAL	RESP ENG	FWANG 9/22/05	SIZE B DWG. NO. INM27001 REV. C
	FINISH	MFG ENG	
NEXT ASSY	USED ON	QUAL ENG	
APPLICATION			DO NOT SCALE DRAWING